Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

Board Level Cooling – Hat Section 5000

BOARD LEVEL COOLING – Hat Section 5000

Hat Section 5000 is a series of hat channel board level heat sinks designed to cool TO-3 devices. Representative image only.

ORDERING INFORMATION

Part Number	Device Type
506003B00000G	TO-3
506007B00000G	TO-3

HEAT SINK DETAILS

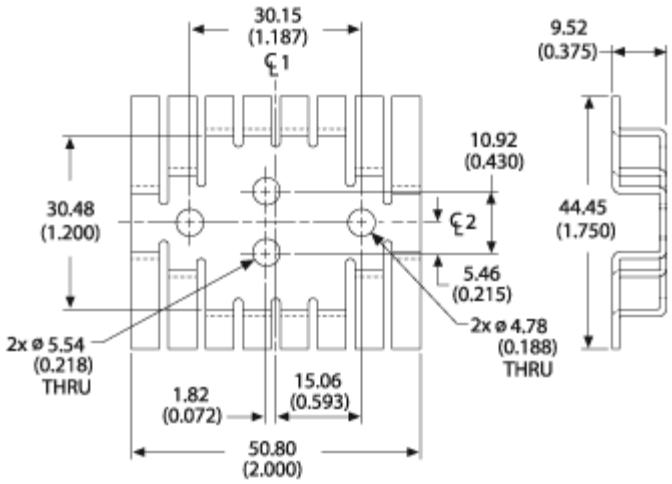
Property	Details
Material	Aluminum
Finish	Black Anodize
Device Attachment Options	Requires Mounting Kit
Thermal Interface Material	-

Property	Details
Heat Sink Width (mm)	44.45
Heat Sink Length (mm)	50.80
Heat Sink Height (mm)	9.53
Heat Sink Mounting Direction	Horizontal

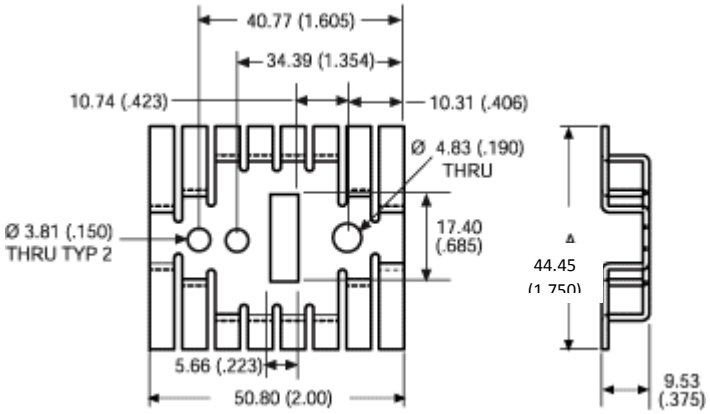
MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

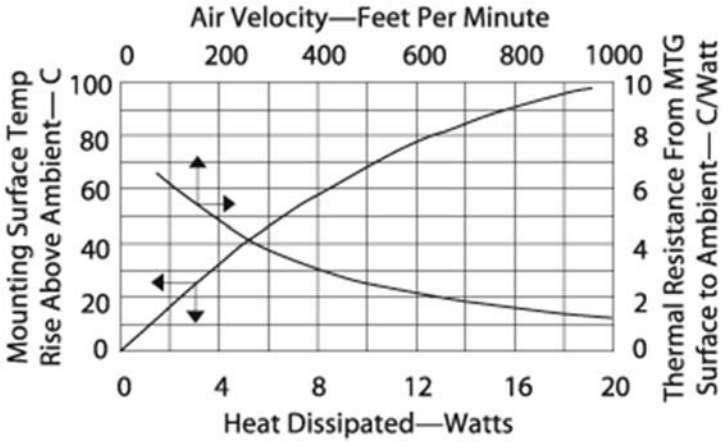
Part Number: 506003B00000G



Part Number: 506007B00000G



USA: 1.855.322.2843
EUROPE: 39.051.764002
ASIA: 86.21.6115.2000 x8122


Air Velocity—Feet Per Minute
0
200
400
600
800
1000
Mounting Surface Temp Rise Above Ambient—C
100
80
60
40
20
0
Thermal Resistance From MTG Surface to Ambient—C/Watt
10
8
6
4
2
0
0
4
8
12
16
20
Heat Dissipated—Watts